

**AMENDMENTS TO THE SPECIFICATION:**

**Please amend the paragraph bridging page 1, line 28 - page 2, line 1, as follows:**

The inventors of this application identified the following problems ~~occurring~~ occurred when the plastic substrate fabricated as described above is handled in actual manufacturing steps.

**Please amend the paragraph beginning at page 2, line 2, as follows:**

~~That is, referring~~ Referring to a side view shown in FIG. 2A, air 214 enters between the thermally activatable adhesive 212 and the plastic substrate 201. Even when trying to pull out the air left between the thermally activatable adhesive 212 and the plastic substrate 201, the adhesive 212 blocks a passage along which the air escapes ~~is pulled out~~ to the outside and therefore, ~~[[the]]~~ air is always ~~[[is]]~~ left between the adhesive 212 and substrate 201 ~~therebetween~~. Thereafter, the plastic substrate 201 supported by the support substrate 203 is rinsed with pure water and chemical solution, and then dried at a temperature of 130-170~~°-degree-~~C~~[[.]]~~. Then, an alignment material, ~~that is to be~~ heated at low processing temperatures, is applied to the transparent electrode 213 on the plastic substrate 201 by printing techniques and heated at a temperature of 80-180~~°-degree-~~C~~[[.]]~~. Subsequently, the heated alignment material is rubbed to form an alignment film and rinsed with pure water, and then dried at a temperature of 130-170~~°-degree-~~C~~[[.]]~~.

**Please amend the paragraph beginning at page 2, line 18, as follows:**

The plastic substrate 201, having been subjected to the aforementioned heat treatment, is deformed because the air 214 thermally expands and grows into ~~[[as]]~~ a large bubble. In some cases, the plastic substrate 201 is broken by expansion of bubble.

**Please amend the paragraph beginning at page 2, line 22, as follows:**

Moreover, as shown in FIG. 2B, an adhesive sealing material 204<sub>1</sub> provided as an thermally cured adhesive and having a specific pattern<sub>1</sub> is formed on the surface (on the side of an alignment film) of the plastic substrate 201<sub>1</sub> which is supported by the support substrate 203, by screen printing techniques or dispensing techniques. Then, a TFT substrate 251 having spacers (not shown) dispersed on the surface thereof and the plastic substrate 201 supported by the support substrate 203 are attached together along the edge with the adhesive sealing material 204 and the two substrates are pressed against each other, and further, heated for 1 to 2 hours at a temperature of 120-160°-degree-C[[.]], resulting in their attachment to ~~each other~~.

**Please amend the paragraph beginning at page 3, line 5, as follows:**

The two substrates<sub>1</sub> attached to each other as described above<sub>1</sub> encounter a situation in which a cell gap between the two substrates becomes non-uniform, i.e., the adhesive sealing material is displaced from its original position[[.]] or the plastic substrate is subject to breakage. This is because variations in the extent to which the thermally activatable adhesive 212 is adhesively attached to the plastic substrate occur and/or the air 214 left between the thermally activatable adhesive 212 and the plastic substrate 201 and subjected to heat treatment<sub>1</sub> in the step of sintering the sealing material<sub>1</sub> expands[[.]] resulting in the deformation and/or flexure of plastic substrate. Furthermore, the fact that the amount of expansion or shrinkage of plastic substrate 201 is larger than that of the support substrate 203 at high processing temperatures (i.e., during sintering of sealing material) also contributes to deformation and/or flexure of plastic substrate. ~~That is,~~ In other words, the adhesion force of the thermally activatable

adhesive 212 provided to the plastic substrate 201 cannot suppress expansion or shrinkage of plastic substrate.

**Please amend the paragraph beginning at page 3, line 23, as follows:**

Moreover, since the plastic substrate, constructed as described above, has the thermally activatable adhesive attached thereto, it needs to be processed through time-consuming steps including an attachment step and a peeling step. ~~[[,]] Thereby, unfavorably increasing the~~ number of process steps is increased.

**Please amend the paragraph beginning at page 4, line 1, as follows:**

An object of the present invention is to provide a method for manufacturing a liquid crystal display device that incorporates therein a plastic substrate that is ~~free from~~ deformation and/or flexure free and ~~never causes~~ does not cause a non-uniformity in ~~[[of]]~~ a cell gap between two substrates ~~during the step of attaching~~ when the two substrates are attached to each other.

**Please amend the paragraph beginning at page 7, line 11, as follows:**

Thereafter, the plastic substrate 1 is rinsed with pure water and chemical solution, and then dried at a temperature of 130-170°~~degree~~-C~~[[.]]~~. Then, an alignment material that is to be heated at low processing temperatures is applied to the ITO film on the plastic substrate 1 by printing techniques and heated at a temperature of 80-180°~~degree~~-C~~[[.]]~~. Subsequently, the heated alignment material is rubbed to form an alignment film 2 and rinsed with pure water, and then dried at a temperature of 130-170°~~degree~~-C~~[[.]]~~.

**Please amend the paragraph beginning at page 9, line 1, as follows:**

Thereafter, as shown in FIG. 5A, an adhesive sealing material 4 as a thermally curable adhesive is formed on a surface (on the side of the alignment film 2) of the plastic substrate 1, which is supported by the glass substrate 3, by screen printing techniques or dispensing techniques to have a specific pattern. The sealing material 4 preferably has an elastic modulus of not less than ~~1.5 times 10 sup 9 Pa~~  $1.5 \times 10^9$  Pa. Then, a TFT substrate 51 having spacers (not shown) dispersed on the surface thereof and the plastic substrate 1 supported by the glass substrate 3 are attached together along the edge with the adhesive sealing material 4. Subsequently, the two substrates are pressed against each other and heated for 1 to 2 hours at a temperature of 120-160°-~~degree~~-C[[.]], resulting in attachment to each other. In this case, the two substrates may be attached together through the sealing material 4 that is formed on a surface of the TFT substrate. Furthermore, when employing a UV-curable material as a sealing material, the plastic substrate is subjected to less thermal stress, further enhancing its flatness.

**Please amend the paragraph beginning at page 10, line 12, as follows:**

Second, in [[the]] this embodiment, the support substrate and the plastic substrate are directly attached together under vacuum conditions without interposing an adhesive therebetween. Since attachment surfaces of the support substrate and the plastic substrate are smooth, the two substrates can be attached together at the smooth attachment surfaces as a boundary under vacuum conditions. Accordingly, air ~~never remains~~ does not remain between the support substrate and the plastic substrate. Furthermore, since the plastic substrate is configured to prevent formation of projections or depressions on its surface, [[a]] the distance between the two substrates does not locally change, permitting uniformity in a cell gap between

the TFT substrate and the plastic substrate, ~~both substrates constituting the liquid crystal display device, to become uniform.~~

**Please amend the paragraph beginning at page 10, line 26, as follows:**

Additionally, the plastic substrate is peeled off from the support substrate by threading the thin strip between the two substrates. ~~and therefore~~ Therefore, the peeling ~~[[off]]~~ of the plastic substrate can be performed very easily, contributing to reducing the number of manufacturing steps.

**Please amend the paragraph beginning at page 11, line 2, as follows:**

When employing the method for manufacturing a liquid crystal display device according to the invention, the plastic substrate is attached to the support substrate under vacuum conditions and there is a lower probability of an air bubble ~~[[is]]~~ being generated between the plastic substrate and the support substrate ~~with lower probability~~ than in a case where the two substrates are attached together via an adhesive. In addition, the extent to which the plastic substrate is expanded or shrunk by heat generated when the sealing material is sintered is ~~made far~~ smaller than that observed when the plastic substrate attached to the support substrate via an adhesive that is expanded or shrunk. Accordingly, even after the plastic substrate and the TFT substrate are attached together along the edge with the sealing material, the plastic substrate is able to maintain its flatness and therefore, the two substrates are spaced a uniform distance apart from each other, i.e., fabricated to maintain a constant cell gap therebetween as desired.